

In re Patent Application of:
BYUN ET AL.
Serial No. **NOT YET ASSIGNED**
Filed: **HEREWITH**
_____ /

In the Specification:

Please replace the paragraph beginning at page 9, line 1, with the following rewritten paragraph:

Here, upon considering the heating temperature of the bonding process of the circuit board, if the softening point of the thermoplastic resin is ~~less than 60~~ more than 150°C, since the thermoplastic resin is not softened, the bonding force between the circuit boards is lower, and electric connection becomes inferior. Meanwhile, if the softening point of the thermoplastic resin is ~~more than 150~~ less than 60°C, since the film layer formed in the side portions 12-2 of the electrode in the circuit patterns are damaged, the electrodes have a short circuit due to the conductive particles.